HAT1044M

Silicon P Channel Power MOS FET Power Switching

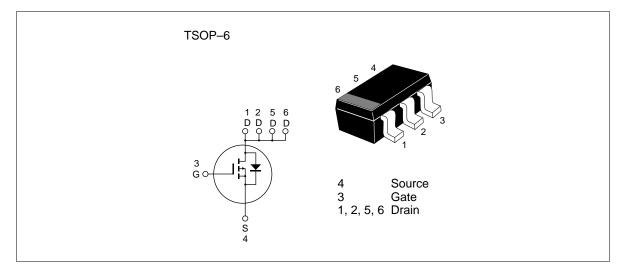
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ADE-208-753C(Z) Preliminary 4th. Edition December 1998

Features

- Low on-resistance
- Low drive current
- · High density mounting
- 4.5V gate drive device can be driven from 5V source

Outline





HAT1044M

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	_D *2	-4.5	A
Drain peak current	l _{D(pulse)} *1	-18	A
Body-drain diode reverse drain current	_{DR} *2	-4.5	A
Channel dissipation	Pch _(pulse) *2	2.0	W
	Pch _(continuous) *3	1.05	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

- 2. When using the alumina ceramic board (50 x 50 x 0.7 mm), PW≤ 5s,Ta=25°C
- 3. When using the alumina ceramic board (50 x 50 x 0.7 mm) ,Ta=25°C

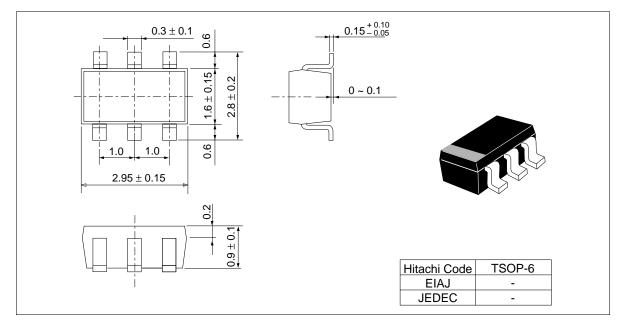
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	_	_	V	$I_{D} = 10 \text{mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-1.0	_	-2.5	V	$V_{DS} = -10V$, $I_D = -1mA$
Static drain to source on state	$R_{\scriptscriptstyle DS(on)}$	_	50	60	$m\Omega$	$I_D = -3A$, $V_{GS} = -10V^{*1}$
resistance	$R_{\text{DS(on)}}$	_	80	105	$m\Omega$	$I_D = -3A, V_{GS} = -4.5V^{*1}$
Forward transfer admittance	y _{fs}	3	5.5	_	S	$I_D = -3A$, $V_{DS} = -10V^{*1}$
Input capacitance	Ciss	_	600	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	220	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	150	_	pF	f = 1MHz
Turn-on delay time	$t_{d(on)}$	_	12	_	ns	$V_{GS} = -10V, I_{D} = -3A$
Rise time	t _r	_	85	_	ns	$R_L = 3.3\Omega$
Turn-off delay time	t _{d(off)}	_	55	_	ns	_
Fall time	t _f	_	55	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.95	_	V	$IF = -4.5A, V_{GS} = 0^{*1}$
Body–drain diode reverse recovery time	t _{rr}	_	50	_	ns	$IF = -4.5A, V_{GS} = 0$ diF/ dt =-20A/ μ s

Note: 1. Pulse test

Package Dimensions

Unit: mm



Cautions

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom

Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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